



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL31B475KBHNFNE

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 4.7 µF, 50V, ±10%, X7R, 1206

## A. Samsung Part Number

<u>CL</u> <u>31</u> <u>B</u> <u>475</u> <u>K</u> <u>B</u> <u>H</u> <u>N</u> <u>F</u> <u>N</u> <u>E</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

| ① Series      | Samsung Multi-layer Ceramic Capacitor |                 |                               |  |  |
|---------------|---------------------------------------|-----------------|-------------------------------|--|--|
| ② Size        | 1206 (inch code)                      | L: 3.2 ± 0.2 mm | W: 1.6 ± 0.2 mm               |  |  |
| ③ Dielectric  | X7R                                   | Inner electrode | Ni                            |  |  |
| Capacitance   | <b>4.7</b> μF                         | Termination     | Cu                            |  |  |
| ⑤ Capacitance | ±10 %                                 | Plating         | Sn 100% (Pb Free)             |  |  |
| tolerance     |                                       | Product         | Product for POWER application |  |  |
| Rated Voltage | 50 V                                  | Special         | Reserved for future use       |  |  |
| 7 Thickness   | 1.6 ± 0.2 mm                          | ① Packaging     | Embossed Type, 7" reel        |  |  |

## **B. Samsung Reliablility Test and Judgement condition**

|                   | Performance  | Test condition                        |  |  |  |
|-------------------|--|---------------------------------------|--|--|--|
| Capacitance       | Within specified tolerance                                   | 1kHz±10% 1.0±0.2Vrms                  |  |  |  |
| Tan δ (DF)        | 0.1 max.   |                                       |  |  |  |
| Insulation        | 10,000Mohm or 100Mohm⋅µF                                     | Rated Voltage 60~120 sec.             |  |  |  |
| Resistance        | Whichever is Smaller   |                                       |  |  |  |
| Appearance        | No abnormal exterior appearance                              | Microscope (×10)                      |  |  |  |
| Withstanding      | No dielectric breakdown or                                   | 250% of the rated voltage             |  |  |  |
| Voltage           | mechanical breakdown   |                                       |  |  |  |
| Temperature       | X7R  |                                       |  |  |  |
| Characterisitcs   | (From -55℃ to 125℃, Capacitance change shoud be within ±15%) |                                       |  |  |  |
| Adhesive Strength | No peeling shall be occur on the                             | 500g⋅F, for 10±1 sec.                 |  |  |  |
| of Termination    | terminal electrode   |                                       |  |  |  |
| Bending Strength  | Capacitance change : within ±12.5%                           | Bending to the limit (1mm)            |  |  |  |
|                   |  | with 1.0mm/sec.                       |  |  |  |
| Solderability     | More than 75% of terminal surface                            | SnAg3.0Cu0.5 solder                   |  |  |  |
|                   | is to be soldered newly                                      | 245±5℃, 3±0.3sec.                     |  |  |  |
|                   |  | (preheating : 80~120 ℃ for 10~30sec.) |  |  |  |
|                   |  |                                       |  |  |  |
| Resistance to     | Capacitance change: within ±7.5%                             | Solder pot : 270±5℃, 10±1sec.         |  |  |  |
| Soldering heat    | Tan δ, IR : initial spec.                                    |                                       |  |  |  |

|                  | Performance               |            | Test condition   |  |
|------------------|---------------------------|------------|--|--|
| Vibration Test   | Capacitance change: with  | hin ±5%    | Amplitude : 1.5mm  |  |
|                  | Tan δ, IR : initial spec. |            | From 10Hz to 55Hz (return : 1min.)                                   |  |
|                  |                           |            | 2hours $\times$ 3 direction (x, y, z)                                |  |
| Moisture         | Capacitance change: with  | hin ±12.5% | With rated voltage   |  |
| Resistance       | Tan δ : 0.125 max         |            | 40±2℃, 90~95%RH, 500+12/-0hrs  |  |
|                  | IR: 12.5MΩ·μF or Over     |            |  |  |
| High Temperature | Capacitance change: with  | hin ±12.5% | With 150% of the rated voltage                                       |  |
| Resistance       | Tan δ: 0.125 max          |            | Max. operating temperature   |  |
|                  | IR : 25MΩ·μF or Over      |            |  |  |
|                  |                           |            | 1000+48/-0hrs  |  |
| Temperature      | Capacitance change: with  | hin ±7.5%  | 1 cycle condition  |  |
| Cycling          | Tan δ, IR : initial spec. |            | Min. operating temperature $\rightarrow$ 25 $^{\circ}$ C             |  |
|                  |                           |            | $ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}$ C |  |
|                  |                           |            | 5 cycle test   |  |

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C , 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.